



1A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

FEATURES:

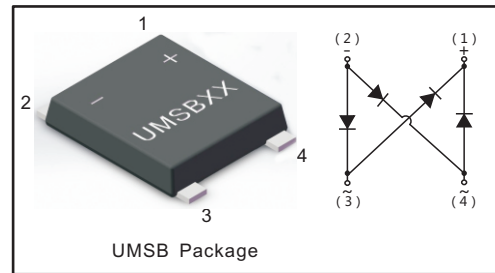
- Glass Passivated Chip Junction
- Reverse Voltage - 100 to 1000 V
- Forward Current - 1.0 A
- High Surge Current Capability
- Designed for Surface Mount Application

MECHANICAL DATA

- Case: UMSB
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 0.234g / 0.00825oz

PINNING

PIN	DESCRIPTION
1	Output Anode ( + )
2	Output Cathode ( - )
3	Input Pin ( ~ )
4	Input Pin ( ~ )



Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	MSB10B	MSB10D	MSB10G	MSB10J	MSB10K	MSB10M	Units
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	100	200	400	600	800	1000	V
Average Rectified Output Current	$I_O$	1.0						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	$I_{FSM}$	35						A
Maximum Forward Voltage at 1.0 A	$V_F$	1.1						V
Maximum DC Reverse Current at Rated DC Blocking Voltage @ $T_A=25\text{ }^\circ\text{C}$ @ $T_A=125\text{ }^\circ\text{C}$	$I_R$	5 100						$\mu\text{A}$
Typical Junction Capacitance ( Note1 )	$C_j$	18						pF
Typical Thermal Resistance ( Note2 )	$R_{\theta JA}$ $R_{\theta JC}$ $R_{\theta JL}$	70 15 40						$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_j, T_{stg}$	-55 ~ +150						$^\circ\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4×1.5"×1.5" ( 3.81×3.81 cm ) copper pad.



Fig.1 Average Rectified Output Current Derating Curve

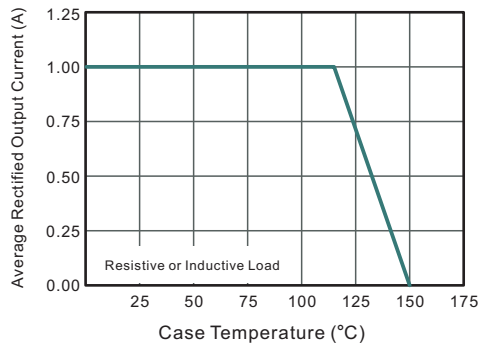


Fig.2 Typical Reverse Characteristics

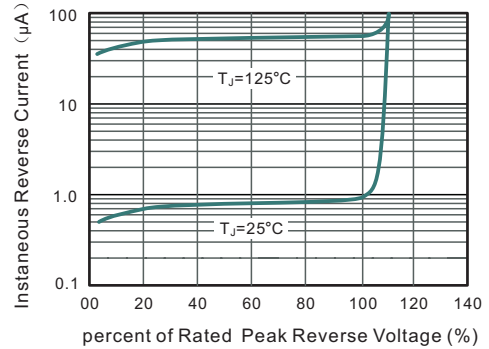


Fig.3 Typical Instantaneous Forward Characteristics

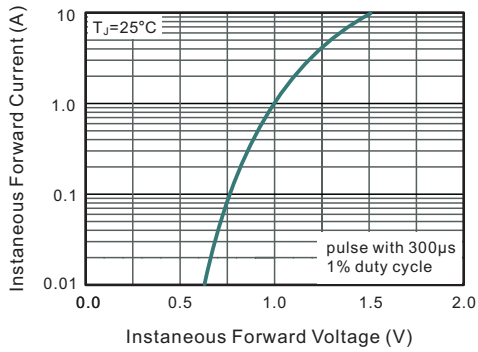


Fig.4 Typical Junction Capacitance

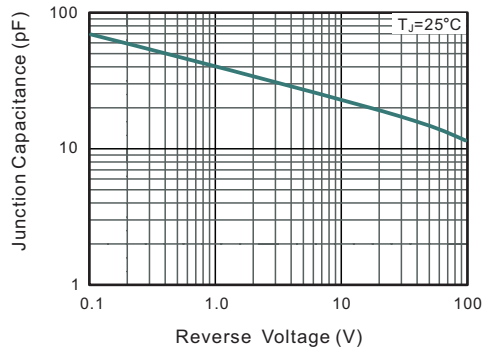


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

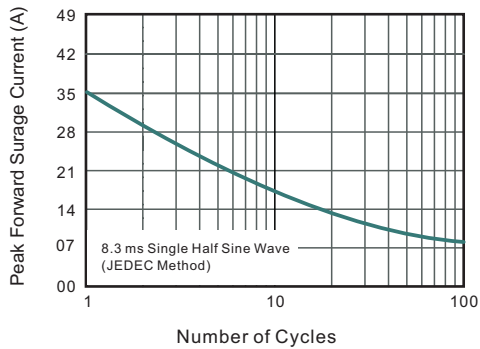
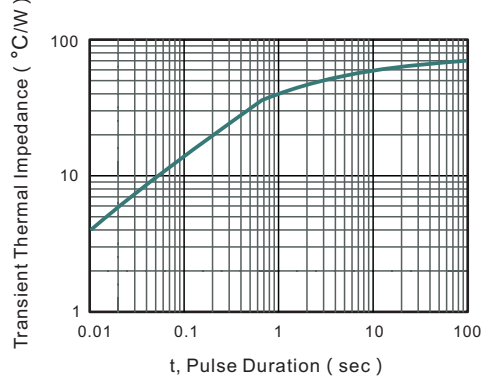


Fig.6- Typical Transient Thermal Impedance

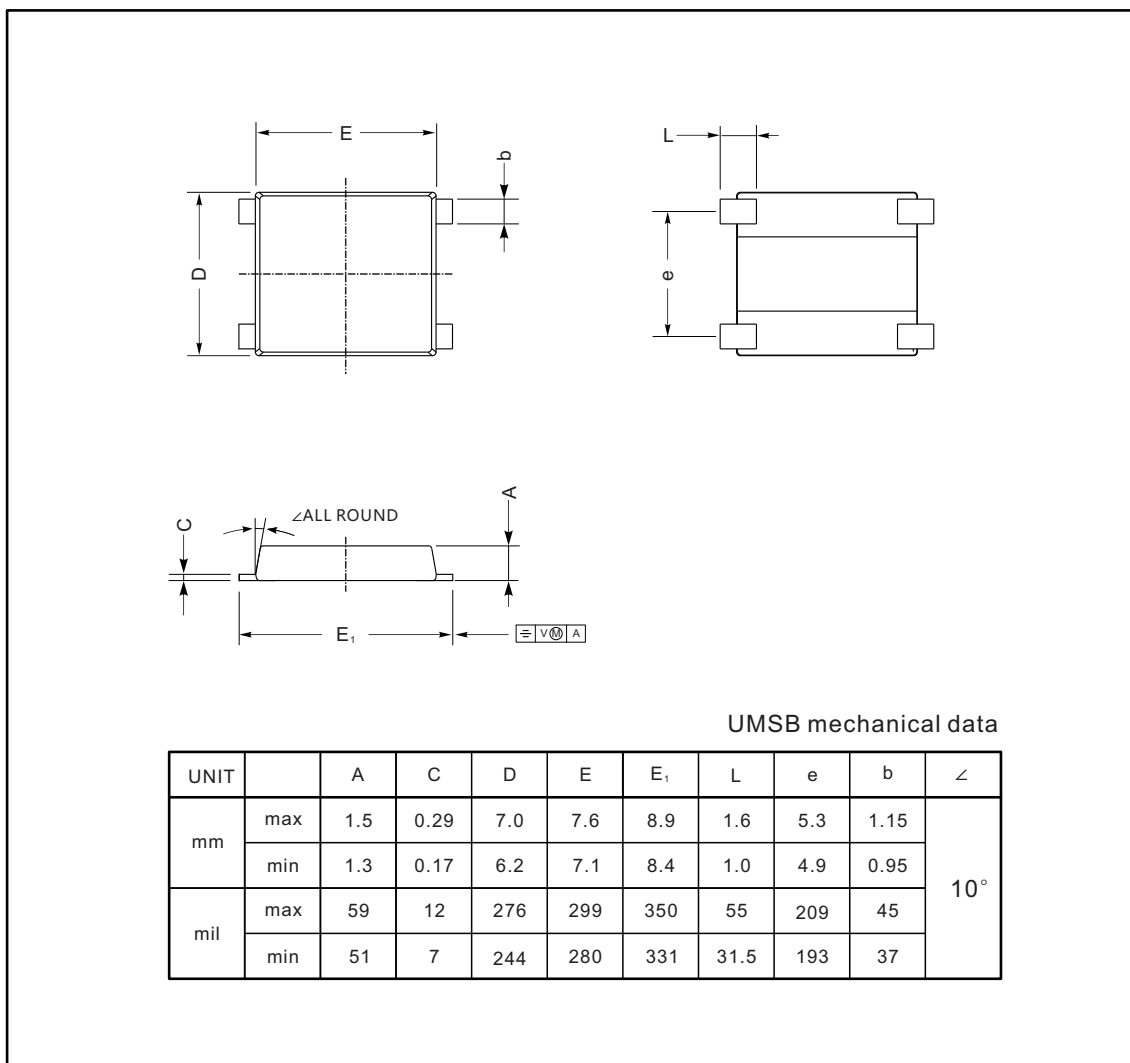




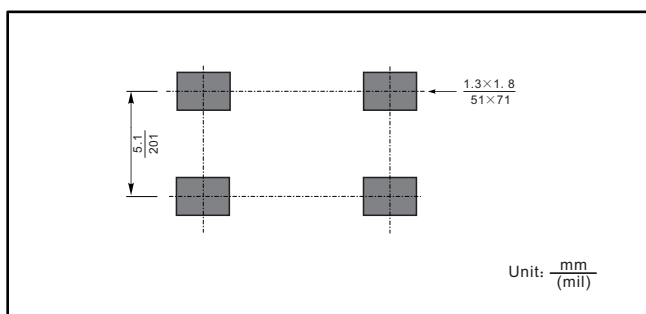
PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

UMSB



The recommended mounting pad size



Marking

Type number	Marking code
MSB10B	MB10B
MSB10D	MB10D
MSB10G	MB10G
MSB10J	MB10J
MSB10K	MB10K
MSB10M	MB10M